

Ankit More

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RESEARCH INTERESTS Digital, Analog and Mixed Signal Integrated Circuits, Radio Frequency Integrated Circuits (RFIC), Low Power VLSI Circuits, 3-D ICs and Post-CMOS Interconnects.

- EDUCATION ◇ **Ph.D., Electrical Engineering**, (September 2009 – current).
Drexel University, Philadelphia, PA.
Topic: Wireless interconnects for inter and intra-chip communication
- ◇ **M.S., Electrical Engineering**, GPA: 3.95 (Summa-cum-laude), (June 2009).
Drexel University, Philadelphia, PA.
Concentration: Systems and Control
- ◇ **B.S., Electrical Engineering**, GPA: 3.95 (Summa-cum-laude), (June 2009).
Drexel University, Philadelphia, PA.
Concentration: Advanced Electronics

- PROFESSIONAL EXPERIENCE ◇ **Research Assistant and Teaching Assistant**, (September 2009 – current)
Department of Electrical and Computer Engineering
Drexel University, Philadelphia, PA
- Research Assistant in the VLSI Lab working on
 - VLSI design and
 - 3D electro-magnetic modeling.
 - Teaching Assistant in the ECE Department for
 - Electrical Engineering Laboratory 3 (ECE-L 303) (Fall, AY 2009 – 2010).
 - Electrical Engineering Laboratory 4 (ECE-L 304) (Winter, AY 2009 – 2010).
- ◇ **Internship - Research and Development Engineering** , (April 2008 – September 2008)
Siemens Energy and Automation, Spring House, PA, USA
- Developed automated software testing tools for distributed control systems software.
 - Co-authored patent application for an expandable automated testing concept, awaiting filing of application.
 - Assisted in Virtual Machine management using VMWare.
- ◇ **Internship - Assistant Project Manager** , (September 2006 – March 2007)
Maida Engineering Inc, Fort Washington, PA, USA
- Assisted in design of power distribution systems to manufacturing plants.
 - Created two dimensional CAD layouts using AutoCAD for electrical systems according to the NEC.

- SELECTED PROJECTS ◇ **Wireless Interconnect Design, Drexel University**
- Design of on-chip antennas for inter and intra-chip communication for planar and 3D ICs.
 - IC design in IBM 90 nm technology.
 - Full-wave 3D Finite Element Method (FEM) electro-magnetic simulations.
 - Simulation of leakage current, electro-magnetic compatibility and interference.
- ◇ **Rotary Clock Custom Integrated Circuit, Drexel University**
- Design of custom and regular rotary rings.
 - IC design in AMI C5N 0.5 μm process using MOSIS fabrication process.
- ◇ **Senior Design, Unmanned Aerial Vehicle (UAV), Drexel University**
- Autonomous control for stable hover of miniature unmanned aerial vehicles.
 - Designed a control system using embedded C code on Texas Instruments TMS320 DSP.
 - Designed custom peripheral circuits for DSP isolation and sensor connection.
 - Co-sponsored by the U.S. Army Research Lab and the MEM Department, Drexel University.

- PUBLICATIONS
- ◇ Ankit More and Baris Taskin, *Wireless Interconnects for Inter-tier Communication on 3-D ICs*, to appear in the Proceedings of the European Microwave Integrated Circuits Conference (EuMIC), September 2010.
 - ◇ Ankit More and Baris Taskin, *Simulation Based Feasibility Study of Wireless RF Interconnects for 3D ICs*, to appear in the Proceedings of the IEEE Computer Society Annual Symposium on VLSI (ISVLSI), July 2010.
 - ◇ Ankit More and Baris Taskin, *Electromagnetic Compatibility of CMOS On-chip Antennas*, to appear in the Proceedings of the IEEE International Symposium on Antennas and Propagation (APS), July 2010.
 - ◇ Ankit More and Baris Taskin, *Simulation Based Study of Wireless RF Interconnects for Practical CMOS Implementation*, to appear in the Proceedings of the System Level Interconnect Prediction (SLIP), June 2010.
 - ◇ Ankit More and Baris Taskin, *Electromagnetic Interaction of On-Chip Antennas and CMOS Metal Layers for Wireless IC Interconnects*, to appear in the Proceedings of the IEEE/ACM Great Lakes Symposium on VLSI (GLSVLSI), May 2010.
 - ◇ Ankit More and Baris Taskin, *Leakage Current Analysis for Intra-Chip Wireless Interconnects*, Proceedings of the IEEE International Symposium on Quality Electronic Design (ISQED), pp. 49–53, March 2010.
- SKILLS
- ◇ C, C++, Basic Java, CLisp, XML, XSLT, JScript, VBScript
 - ◇ Cadence – Virtuoso Suite, Spectre, PSpice
Synopsys – Design Compiler, ICC Compiler, HSpice
 - ◇ Ansoft – High Frequency Structure Simulator (HFSS), Q3D extractor
Agilent – Advanced Design Systems (ADS)
 - ◇ Matlab, Maple, Labview, AutoCAD, Quick Test Professional
 - ◇ L^AT_EX, Office Suites
 - ◇ Unix, Linux, MS Windows
- ACADEMIC HONORS AND AWARDS
- ◇ Graduated with 1st Honors (highest GPA among the graduating class) from the Department of Electrical and Computer Engineering, Drexel University, 2009.
 - ◇ Dean’s List, College of Engineering, Drexel University, 2005 – 2009.
 - ◇ A.J. Drexel Academic Scholarship, Drexel University, 2005 – 2009.
 - ◇ John Raymond Vollmar Endowed Scholarship, Drexel University, 2007 – 2008.
 - ◇ Harry E. Muchnic Scholarship, Drexel University, 2008 – 2009.
 - ◇ Tau Beta Pi National Scholarship, 2008 – 2009.
 - ◇ Member, Tau Beta Pi, Engineering Honor Society.
 - ◇ Member, Eta Kappa Nu, Electrical Engineering Honor Society.
- RELEVANT COURSEWORK
- ◇ CMOS VLSI Design, Computer Architecture, CAD for VLSI Design, Digital IC Design, Stochastic Systems, Microwave Passive Systems, Microwave Active Systems, RF Electronics, Numerical Analysis Methods.
- REFERENCES
- ◇ **Dr. Moshe Kam**
Department Head and Robert Quinn Professor
Department of Electrical and Computer Engineering
Drexel University, Philadelphia, PA
E-mail: kam@minerva.ece.drexel.edu
 - ◇ **Dr. B.C. Chang**
Professor, Department of Mechanical Engineering and Mechanincs
Drexel University, Philadelphia, PA
E-mail: bchang@coe.drexel.edu

◇ **Dr. Baris Taskin**

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